**NI/CU POLYESTER CONDUCTIVE FABRIC TAPE**

Laird Technologies' Conductive Fabric Tape 86749 offers exceptional conformability and conductivity for dynamic flex applications. It is constructed of nickel/copper metallized fabric with a conductive pressure sensitive adhesive (PSA). This reliable tape design provides outstanding shielding performance while offering superior abrasion and corrosion resistance under high dynamic flex conditions. The 86749 is a halogen free product and can be supplied in tape or further customized to application by die-cutting or hole punching.

FEATURES

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity of $< 0.06 \Omega/\square$ provides excellent conductivity
- Shielding effectiveness of >62 dB across a wide spectrum of frequencies

MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers

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USA: +1.866.928.8181

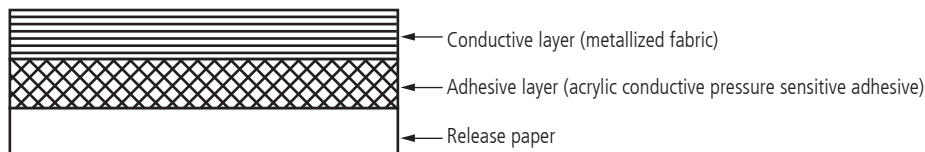
Europe: +49.0.8031.2460.0

Asia: +86.755.2714.1166

Item	Unit	Value	Test Method
Thickness	mm	0.060 mm ± 0.01	-
Peel Adhesion	Kgf / 25 mm	>0.8	PSTC 101*
Shear Adhesion			
at R.T.	Hrs	>72	PSTC 107#
at 80°C	Hrs	>5	PSTC 107#
Tensile Strength	Kgf / 25 mm	>7	
Operation Temperature	°C	0-80	
Surface Resistivity (Fabric Side)	Ω/□	<0.06	ASTM F390
Z-axial Resistance	Ω	<0.04	
Shielding Effectiveness*			ASTM D4935
at 100 MHz	dB	62	
at 1GHz	dB	68	
Package Dimensions (Max. Width: 1000 mm)	M	W: Dimension by Customer Spec L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		Six Months	

*:Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm +:Typical value

COMPOSITION OF PRODUCT



APPLICATION TECHNIQUES

- Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
- To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
- Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.